

ABSTRACT

A semiconductor package without substrate and method of manufacturing the same includes providing an interim substrate which has a front surface covered with a solder mask at selected locations. The front surface not covered by the solder mask are
5 formed with a plurality of lead layers and die pad layers. The top side of the die pad layer adheres to a chip. The chip and lead layers are connected electrically by a plurality of bonding wires. The chip, bonding wires, solder mask, lead layer and die pad layer are
10 covered by a molded resin. After the package is singulated, the interim substrate is removed by etching to form the semiconductor package without substrate.